

# 4V Drive Nch MOSFET

## RP1L080SN

### ●Structure

Silicon N-channel MOSFET

### ●Features

- 1) Low on-resistance.
- 2) Fast switching speed.
- 3) Drive circuits can be simple.
- 4) Parallel use is easy.

### ●Application

Switching

### ●Packaging specifications

| Type      | Package                      | Taping |
|-----------|------------------------------|--------|
|           | Code                         | TR     |
|           | Basic ordering unit (pieces) | 1000   |
| RP1L080SN |                              | ○      |

### ●Absolute maximum ratings (T<sub>a</sub> = 25°C)

| Parameter                    | Symbol            | Limits             | Unit   |
|------------------------------|-------------------|--------------------|--------|
| Drain-source voltage         | V <sub>DSS</sub>  | 60                 | V      |
| Gate-source voltage          | V <sub>GSS</sub>  | ±20                | V      |
| Drain current                | Continuous        | I <sub>D</sub>     | ±8.0 A |
|                              | Pulsed            | I <sub>DP</sub> *1 | ±32 A  |
| Source current (Body Diode)  | Continuous        | I <sub>S</sub>     | 1.6 A  |
|                              | Pulsed            | I <sub>SP</sub> *1 | 32 A   |
| Power dissipation            | P <sub>D</sub> *2 | 2.0                | W      |
| Channel temperature          | T <sub>ch</sub>   | 150                | °C     |
| Range of storage temperature | T <sub>stg</sub>  | -55 to +150        | °C     |

\*1 Pw ≤ 10μs, Duty cycle ≤ 1%

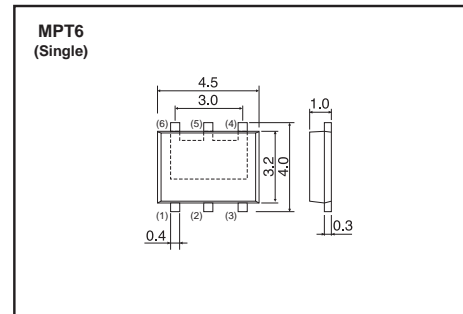
\*2 Mounted on a ceramic board

### ●Thermal resistance

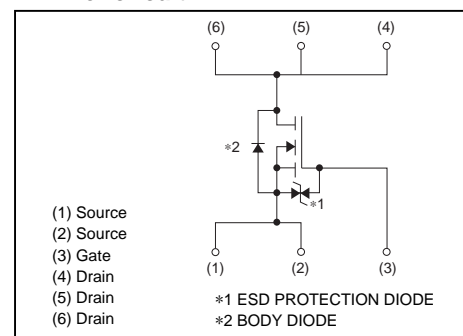
| Parameter          | Symbol                  | Limits | Unit   |
|--------------------|-------------------------|--------|--------|
| Channel to Ambient | R <sub>th(ch-a)</sub> * | 62.5   | °C / W |

\* Mounted on a ceramic board

### ●Dimensions (Unit : mm)



### ●Inner circuit



●Electrical characteristics (T<sub>a</sub> = 25°C)

| Parameter                               | Symbol                | Min. | Typ. | Max. | Unit | Conditions                                  |
|---|-----------------------|------|------|------|------|---|
| Gate-source leakage                     | I <sub>GSS</sub>      | -    | -    | ±10  | μA   | V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V  |
| Drain-source breakdown voltage          | V <sub>(BR)DSS</sub>  | 60   | -    | -    | V    | I <sub>D</sub> =1mA, V <sub>GS</sub> =0V    |
| Zero gate voltage drain current         | I <sub>DSS</sub>      | -    | -    | 1    | μA   | V <sub>DS</sub> =60V, V <sub>GS</sub> =0V   |
| Gate threshold voltage                  | V <sub>GS(th)</sub>   | 1.0  | -    | 3.0  | V    | V <sub>DS</sub> =10V, I <sub>D</sub> =1mA   |
| Static drain-source on-state resistance | R <sub>DS(on)</sub> * | -    | 17   | 24   | mΩ   | I <sub>D</sub> =8.0A, V <sub>GS</sub> =10V  |
|   |                       | -    | 19   | 27   |      | I <sub>D</sub> =8.0A, V <sub>GS</sub> =4.5V |
|   |                       | -    | 20   | 28   |      | I <sub>D</sub> =8.0A, V <sub>GS</sub> =4.0V |
| Forward transfer admittance             | Y <sub>fs</sub>  *    | 8.5  | -    | -    | S    | I <sub>D</sub> =8.0A, V <sub>DS</sub> =10V  |
| Input capacitance                       | C <sub>iss</sub>      | -    | 1700 | -    | pF   | V <sub>DS</sub> =10V                        |
| Output capacitance                      | C <sub>oss</sub>      | -    | 330  | -    | pF   | V <sub>GS</sub> =0V                         |
| Reverse transfer capacitance            | C <sub>rss</sub>      | -    | 170  | -    | pF   | f=1MHz                                      |
| Turn-on delay time                      | t <sub>d(on)</sub> *  | -    | 18   | -    | ns   | I <sub>D</sub> =4.0A, V <sub>DD</sub> ≒30V  |
| Rise time                               | t <sub>r</sub> *      | -    | 25   | -    | ns   | V <sub>GS</sub> =10V                        |
| Turn-off delay time                     | t <sub>d(off)</sub> * | -    | 70   | -    | ns   | R <sub>L</sub> =7.5Ω                        |
| Fall time                               | t <sub>f</sub> *      | -    | 30   | -    | ns   | R <sub>G</sub> =10Ω                         |
| Total gate charge                       | Q <sub>g</sub> *      | -    | 40   | -    | nC   | V <sub>DD</sub> ≒30V                        |
| Gate-source charge                      | Q <sub>gs</sub> *     | -    | 5.0  | -    | nC   | I <sub>D</sub> =8.0A,                       |
| Gate-drain charge                       | Q <sub>gd</sub> *     | -    | 9.0  | -    | nC   | V <sub>GS</sub> =10V                        |

\*Pulsed

●Body diode characteristics (Source-Drain) (T<sub>a</sub> = 25°C)

| Parameter       | Symbol            | Min. | Typ. | Max. | Unit | Conditions                                |
|-----------------|-------------------|------|------|------|------|---|
| Forward Voltage | V <sub>SD</sub> * | -    | -    | 1.2  | V    | I <sub>s</sub> =8.0A, V <sub>GS</sub> =0V |

\*Pulsed

●Electrical characteristic curves (Ta=25°C)

Fig.1 Typical Output Characteristics ( I )

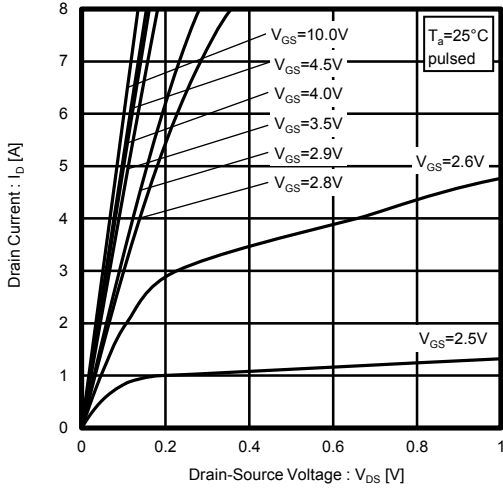


Fig.2 Typical Output Characteristics ( II )

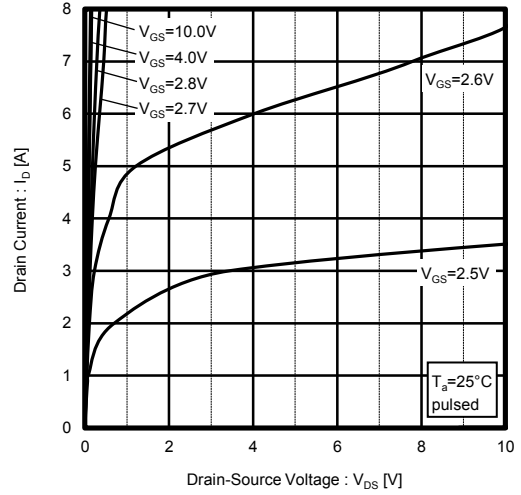


Fig.3 Static Drain-Source On-State Resistance vs. Drain Current

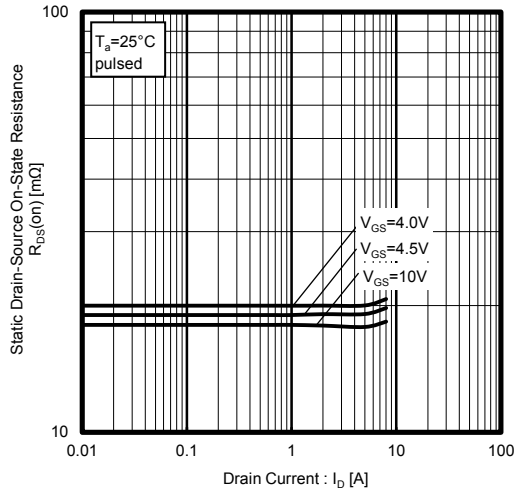


Fig.4 Static Drain-Source On-State Resistance vs. Drain Current

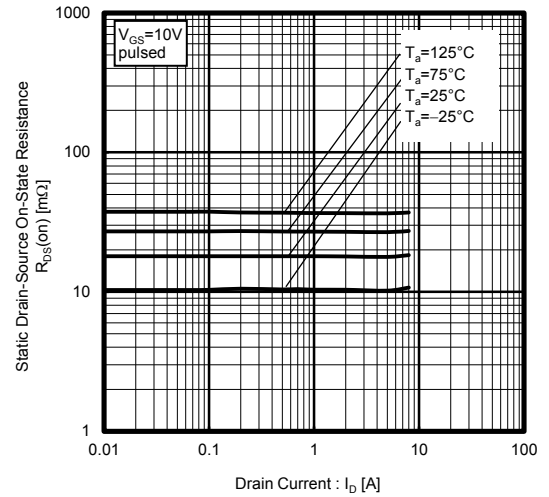


Fig.5 Static Drain-Source On-State Resistance vs. Drain Current

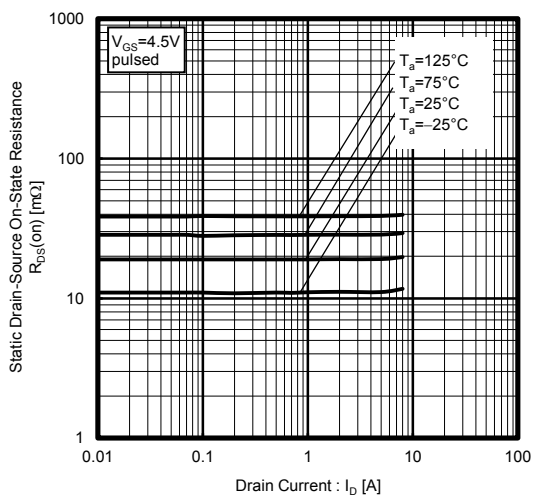


Fig.6 Static Drain-Source On-State Resistance vs. Drain Current

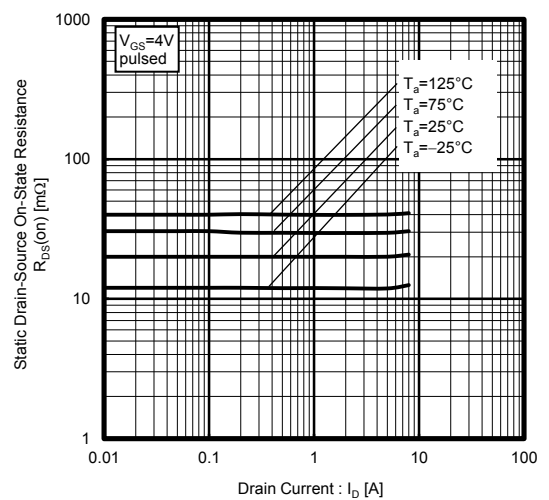


Fig.7 Forward Transfer Admittance vs. Drain Current

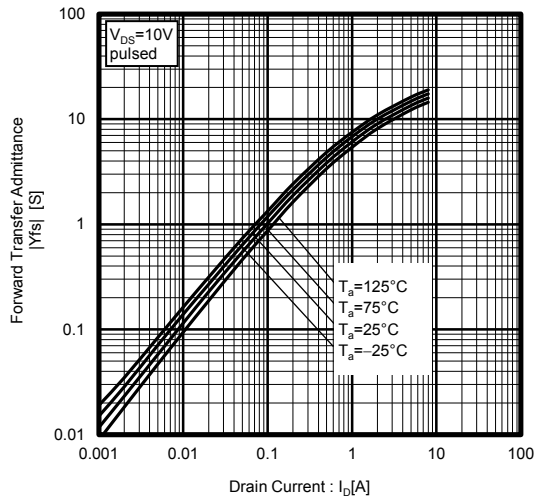


Fig.8 Typical Transfer Characteristics

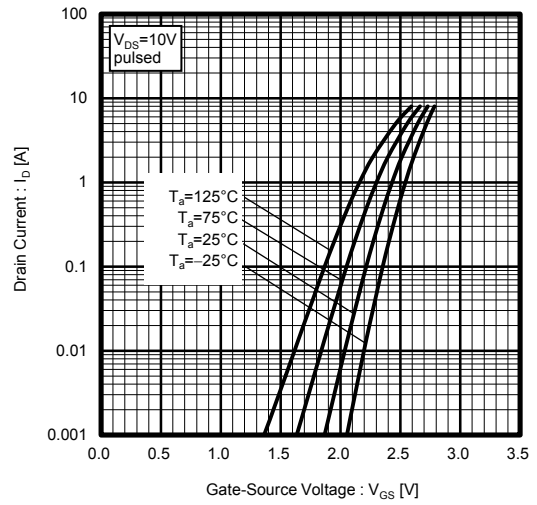


Fig.9 Source Current vs. Source-Drain Voltage

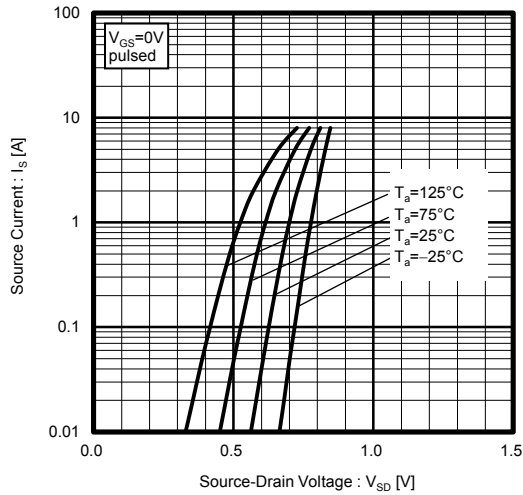


Fig.10 Static Drain-Source On-State Resistance vs. Gate-Source Voltage

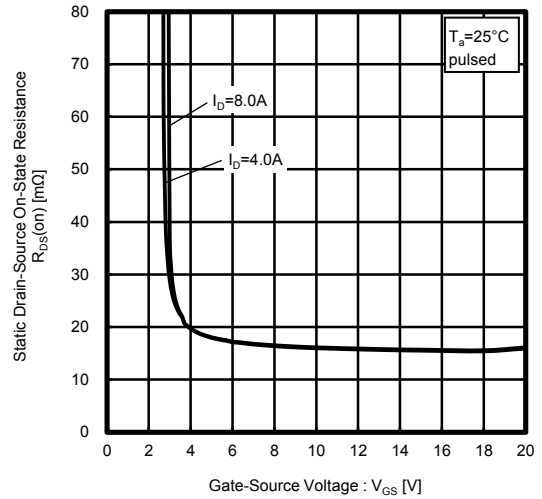


Fig.11 Switching Characteristics

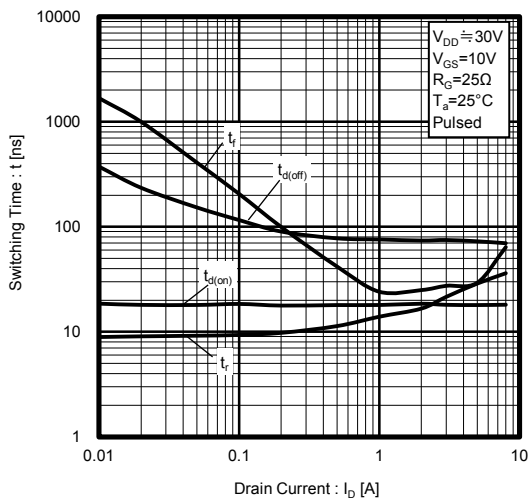


Fig.12 Dynamic Input Characteristics

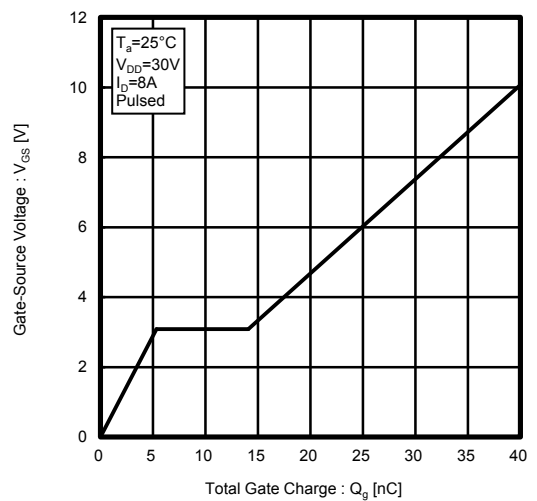


Fig.13 Typical Capacitance vs. Drain-Source Voltage

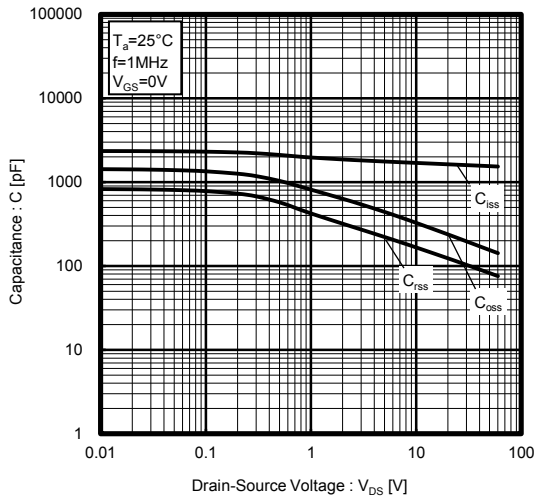


Fig.14 Maximum Safe Operating Area

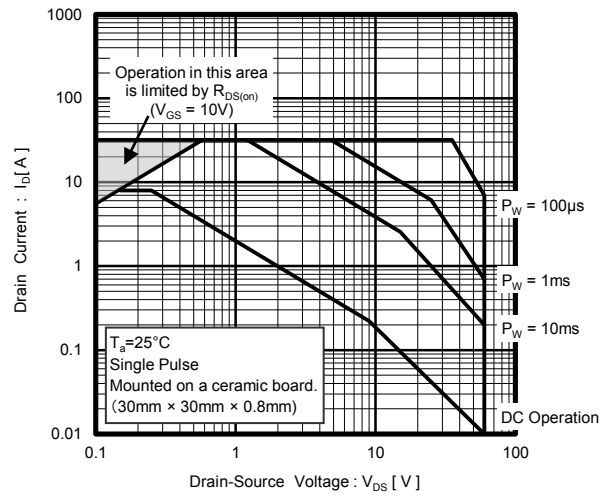
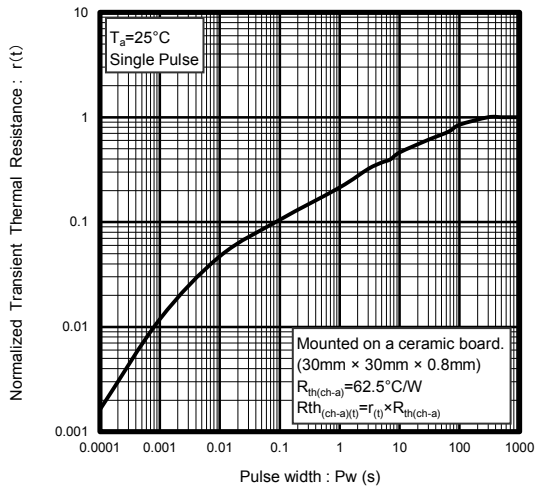


Fig.15 Normalized Transient Thermal Resistance v.s. Pulse Width



● Measurement circuits

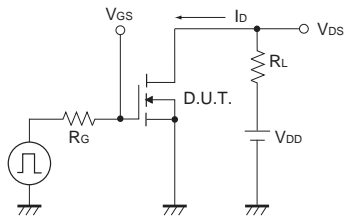


Fig.1-1 Switching Time Measurement Circuit

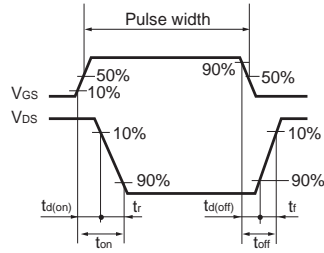


Fig.1-2 Switching Waveforms

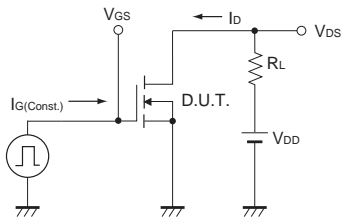


Fig.2-1 Gate Charge Measurement Circuit

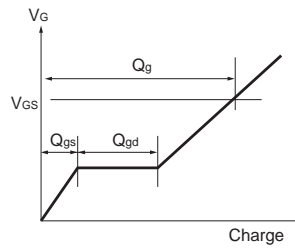


Fig.2-2 Gate Charge Waveform

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